

A/P 581-40

IAP16 Rec'd PCT/PTO 22 SEP 2006

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10/593890

10-03-2006



103315802

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Attorney Docket No. 450100-05480

Applicants: Tetsujiro KONDO, Seiji WADA, Hideo NAKAYA, Takashi TAGO, Ryosuke ARAKI

For: INFORMATION-SIGNAL-PROCESSING APPARATUS, FUNCTIONAL BLOCK CONTROL METHOD, AND FUNCTIONAL BLOCK

U.S. Serial No.: Filed Concurrently Herewith

Corresponding International Application. No.: PCT/JP2005/006204

International Filing Date: March 24, 2005

Mail Stop PCT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

- Names of Conveying Parties: Tetsujiro KONDO, Seiji WADA, Hideo NAKAYA, Takashi TAGO, Ryosuke ARAKI
- Names and addresses of receiving parties: SONY CORPORATION
7-35 Kitashinagawa 6-chome
Shinagawa-Ku, Tokyo 141-0001, Japan
- Nature of Conveyance: Assignment
Execution Date(s): July 4, 2006
- Application No.:
 This document is being filed together with a new application, the execution date of the application is: July 4, 2006.
- Name and address of party to whom the recorded assignment and any correspondence concerning the document should be mailed:

10/593890

William S. Frommer
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09/28/2006 GFREY1 00000156 10593890

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(40.00 DP)

- Total number of applications and patents involved: 1
- Total Fee (37 CFR 3.41): \$40.00
 Fee enclosed.
- Charge Fee Deposit Account No. 50-0320 (Attach duplicate copy of this page if paying by deposit account).
 If any additional fee is required, authorization is hereby given to charge Deposit Account No. 50-0320.

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William S. Frommer
Name of Person Signing

William S. Frommer
Signature

September 22, 2006
Date

00398306.DOC

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ASSIGNMENT

WHEREAS, I, as below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

INFORMATION-SIGNAL-PROCESSING APPARATUS, FUNCTIONAL BLOCK CONTROL METHOD, AND FUNCTIONAL BLOCK

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese Corporation, with offices at 7-35 Kitashinagawa 6-chome, Shinagawa-Ku, Tokyo, 141-0001, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/JP2005/006204, International Filing Date: March 24, 2005.

This assignment executed on the dates indicated below.

Tetsujiro KONDO	
_____ Name of sole or 1st inventor	_____ Execution date of U.S. Patent Application
Tokyo, Japan	
_____ Residence of sole or 1st inventor	
<i>Tetsujiro Kondo</i>	<i>July 4, 2006</i>
_____ Signature of sole or 1st inventor	_____ Date of this assignment

Seiji WADA	
_____ Name of 2nd joint inventor	_____ Execution date of U.S. Patent Application
Kanagawa, Japan	
_____ Residence of 2nd joint inventor	
<i>Seiji Wada</i>	<i>July 4, 2006</i>
_____ Signature of 2nd joint inventor	_____ Date of this assignment

ADDITIONAL INVENTORS

Hideo NAKAYA

Name of 3rd joint inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of 3rd joint inventor

Hideo Nakaya

July 4, 2006

Signature of 3rd joint inventor

Date of this assignment

Takashi TAGO

Name of 4th joint inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of 4th joint inventor

Takashi Tago

July 4, 2006.

Signature of 4th joint inventor

Date of this assignment

Ryosuke ARAKI

Name of 5th joint inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of 5th joint inventor

Ryosuke Araki

July 4, 2006

Signature of 5th joint inventor

Date of this assignment